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Product Change Notification - JAON-26SYMB368 (Printer Friendly)

Date:	29 Jun 2016
Product Category:	Analog (Linear & Mixed Signal) AND Interface; 8-bit Microcontrollers
Notification subject:	CCB 1725 Cancellation Notice: For the qualification of 8390A die attach material for products available 18L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.
Notification text:	<p>PCN Status: Cancellation notification</p> <p>Microchip Parts Affected: This change would have affected products available 18L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.</p> <p>Description of Change: This qualification was originally performed to qualify 8390A die attach material for products available 18L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site</p> <p>Impacts to Data Sheet: Not Applicable</p> <p>Reason for Change: Microchip has decided not to qualify 8390A die attach material for products available 18L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site</p> <p>Change Implementation Status: Not Applicable</p> <p>Estimated First Ship Date: Not Applicable</p> <p>Markings to Distinguish Revised from Unrevised Devices: Not Applicable</p> <p>Revision History: October 13, 2015: Issued initial notification. June 29, 2016: Issued cancellation notice for the proposed qualification of 8390A die attach material for products available 18L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.</p>
Attachment(s):	<p>PCN_JAON-26SYMB368_Affected_CPN.pdf</p> <p>PCN_JAON-26SYMB368_Affected_CPN.xls</p>

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JAON-26SYMB368 - CCB 1725 Cancellation Notice: For the qualification of 8390A die attach material for products available 18L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-26SYMB368
CATALOG_PART_NBR
CF745-04/SO
MCP2140A-I/SO
MCP2140AT-I/SO
MCP2140-I/SO
MCP2140-I/SORVB
MCP2140T-I/SO
MCP2140T-I/SORVB
MCP23008-E/SO
MCP23008T-E/SO
MCP23S08-E/SO
MCP23S08T-E/SO
MCP2515-E/SO
MCP2515-E/SORB2
MCP2515-E/SORB4
MCP2515-I/SO
MCP2515-I/SORB2
MCP2515-I/SORB4
MCP2515T-E/SO
MCP2515T-E/SORB2
MCP2515T-E/SORB4
MCP2515T-I/SO
MCP2515T-I/SORB2
MCP2515T-I/SORB4
MCV18A-I/SO
MCV18E-I/SO
PIC16C54C-04/SO
PIC16C54C-04/SOC04
PIC16C54C-04E/SO
PIC16C54C-04I/SO
PIC16C54C-20/SO
PIC16C54C-20E/SO
PIC16C54C-20I/SO
PIC16C54C-40/SO
PIC16C54CT-04/SO
PIC16C54CT-04/SO098
PIC16C54CT-04/SO120
PIC16C54CT-04I/SO
PIC16C54CT-04I/SO104
PIC16C54CT-04I/SO158
PIC16C54CT-20/SO
PIC16C54CT-20/SO068
PIC16C54CT-20I/SO157
PIC16C56A-04/SO

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Affected Catalog Part Numbers (CPN)

PCN_JAON-26SYMB368
CATALOG_PART_NBR
PIC16C56A-04E/SO
PIC16C56A-04I/SO
PIC16C56A-20/SO
PIC16C56A-20E/SO
PIC16C56A-20I/SO
PIC16C56A-40/SO
PIC16C56AT-04/SO
PIC16C56AT-04/SO027
PIC16C56AT-04/SO040
PIC16C56AT-04I/SO
PIC16C56AT-04I/SO030
PIC16C56AT-04I/SO034
PIC16C56AT-04I/SO038
PIC16C56AT-04I/SO040
PIC16C58B-04/SO
PIC16C58B-04/SO056
PIC16C58B-04E/SO
PIC16C58B-04I/SO
PIC16C58B-04I/SO082
PIC16C58B-20/SO
PIC16C58B-20E/SO
PIC16C58B-20I/SO
PIC16C58B-40/SO
PIC16C58BT-04/SO
PIC16C58BT-04I/SO
PIC16C58BT-04I/SO069
PIC16C58BT-04I/SO080
PIC16C58BT-04I/SO082
PIC16C620A-04/SO
PIC16C620A-04E/SO
PIC16C620A-04I/SO
PIC16C620A-20/SO
PIC16C620A-20E/SO
PIC16C620A-20I/SO
PIC16C620A-40/SO
PIC16C620AT-04/SO
PIC16C620AT-04/SO058
PIC16C620AT-04I/SO
PIC16C620AT-04I/SO076
PIC16C620AT-04I/SO077
PIC16C620AT-20/SO
PIC16C620AT-20I/SO
PIC16C621A-04/SO

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Affected Catalog Part Numbers (CPN)

PCN_JAON-26SYMB368
CATALOG_PART_NBR
PIC16C621A-04E/SO
PIC16C621A-04I/SO
PIC16C621A-20/SO
PIC16C621A-20E/SO
PIC16C621A-20I/SO
PIC16C621A-40/SO
PIC16C621AT-04/SO
PIC16C621AT-04E/SO
PIC16C621AT-04I/SO
PIC16C621AT-04I/SO050
PIC16C621AT-04I/SO081
PIC16C621AT-20/SO
PIC16C621AT-20I/SO
PIC16C621AT-20I/SO051
PIC16C621AT-20I/SO060
PIC16C621AT-20I/SO086
PIC16C622A-04/SO
PIC16C622A-04E/SO
PIC16C622A-04I/SO
PIC16C622A-20/SO
PIC16C622A-20E/SO
PIC16C622A-20I/SO
PIC16C622A-40/SO
PIC16C622AT-04/SO
PIC16C622AT-04E/SO
PIC16C622AT-04I/SO
PIC16C622AT-04I/SO091
PIC16C622AT-04I/SO092
PIC16C622AT-04I/SO093
PIC16C622AT-04I/SO094
PIC16C622AT-20/SO
PIC16C622AT-20/SOC03
PIC16C622AT-20E/SO
PIC16C622AT-20I/SO
PIC16CR54C-04I/SO122
PIC16CR54CT-04/SO124
PIC16CR54CT-20/SO012
PIC16CR58B-04/SO056
PIC16CR58B-04/SO062
PIC16CR58BT-04/SO074
PIC16CR620AT-04I/SO016
PIC16CR620AT-04I/SO017
PIC16CR620AT-04I/SO020

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Affected Catalog Part Numbers (CPN)

PCN_JAON-26SYMB368
CATALOG_PART_NBR
PIC16F1826-E/SO
PIC16F1826-I/SO
PIC16F1826T-E/SO
PIC16F1826T-I/SO
PIC16F1826T-I/SO024
PIC16F1826T-I/SO027
PIC16F1827-E/SO
PIC16F1827-I/SO
PIC16F1827-I/SOC06
PIC16F1827T-E/SO
PIC16F1827T-E/SO035
PIC16F1827T-I/SO
PIC16F1827T-I/SOC06
PIC16F1847-E/SO
PIC16F1847-I/SO
PIC16F1847-I/SOC02
PIC16F1847T-E/SO
PIC16F1847T-I/SO
PIC16F1847T-I/SOC02
PIC16F54-E/SO
PIC16F54-E/SO037
PIC16F54-I/SO
PIC16F54-I/SO023
PIC16F54-I/SO033
PIC16F54-I/SO034
PIC16F54T-E/SO
PIC16F54T-E/SO037
PIC16F54T-E/SO039
PIC16F54T-E/SO040
PIC16F54T-I/SO
PIC16F54T-I/SO028
PIC16F54T-I/SO029
PIC16F54T-I/SO033
PIC16F54T-I/SO034
PIC16F54T-I/SO036
PIC16F627A-E/SO
PIC16F627A-I/SO
PIC16F627AT-E/SO
PIC16F627AT-I/SO
PIC16F627AT-I/SO034
PIC16F628A-E/SO
PIC16F628A-I/SO
PIC16F628A-I/SO065

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Affected Catalog Part Numbers (CPN)

PCN_JAON-26SYMB368
CATALOG_PART_NBR
PIC16F628AT-E/SO
PIC16F628AT-I/SO
PIC16F628AT-I/SO044
PIC16F628AT-I/SO051
PIC16F628AT-I/SO052
PIC16F628AT-I/SO064
PIC16F716-E/SO
PIC16F716-I/SO
PIC16F716-I/SO030
PIC16F716-I/SO4AP
PIC16F716T-E/SO
PIC16F716T-I/SO
PIC16F716T-I/SO048
PIC16F716T-I/SO061
PIC16LC54C-04/SO
PIC16LC54C-04I/SO
PIC16LC54CT-04/SO150
PIC16LC56A-04/SO
PIC16LC56A-04I/SO
PIC16LC58B-04/SO
PIC16LC58B-04I/SO
PIC16LC620A-04/SO
PIC16LC620A-04I/SO
PIC16LC620AT-04/SO
PIC16LC621A-04/SO
PIC16LC621A-04I/SO
PIC16LC621AT-04/SO
PIC16LC621AT-04I/SO
PIC16LC622A-04/SO
PIC16LC622A-04E/SO
PIC16LC622A-04I/SO
PIC16LC622AT-04/SO
PIC16LC622AT-04I/SO
PIC16LCR58BT-04I/SO053
PIC16LF1826-E/SO
PIC16LF1826-I/SO
PIC16LF1826T-I/SO
PIC16LF1827-E/SO
PIC16LF1827-I/SO
PIC16LF1827T-I/SO
PIC16LF1847-E/SO
PIC16LF1847-I/SO
PIC16LF1847T-I/SO

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Affected Catalog Part Numbers (CPN)

PCN_JAON-26SYMB368
CATALOG_PART_NBR
PIC16LF627A-I/SO
PIC16LF627A-I/SOC12
PIC16LF627AT-I/SO
PIC16LF627AT-I/SOC12
PIC16LF628A-I/SO
PIC16LF628AT-I/SO